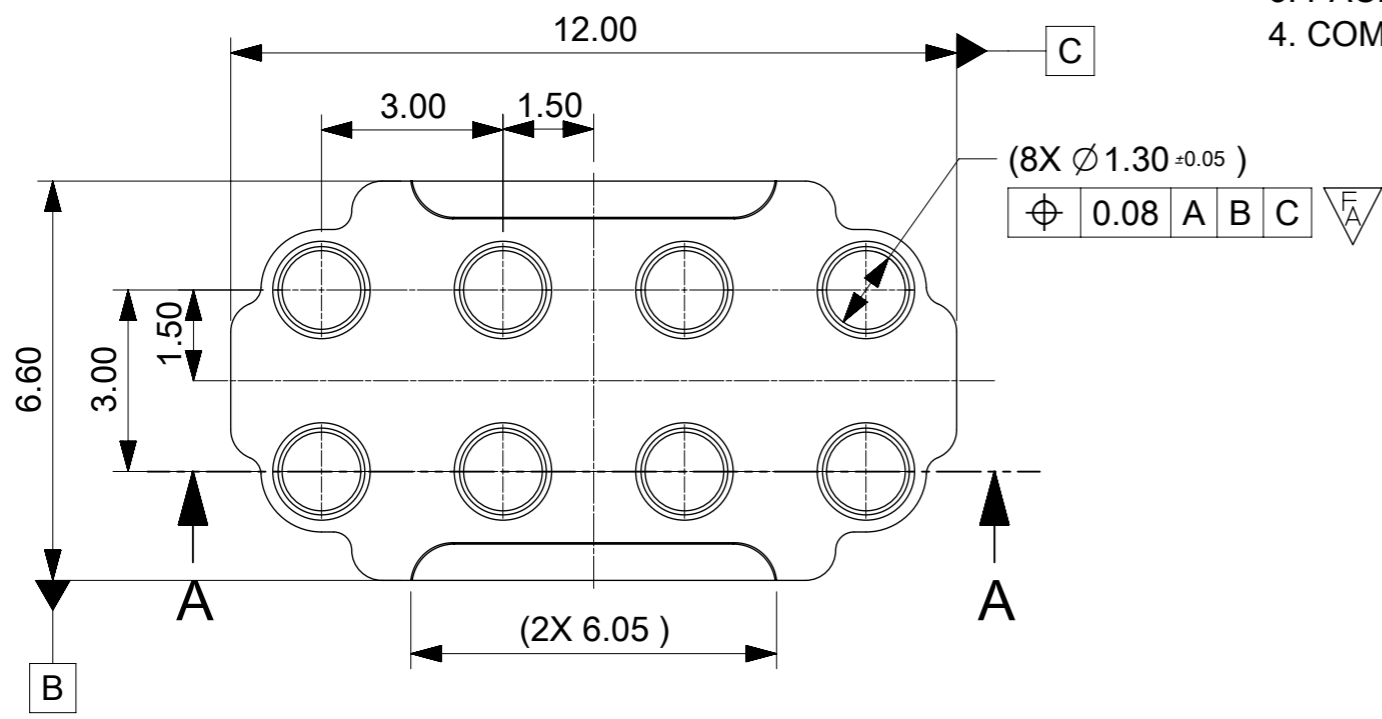


- NOTES:
- MATERIAL :
CARRIER HOUSING: LCP, E130i
METAL PUCKS : PHOS-BRONZE C5210
 - FINISH:
a). NICKEL PLATING:
UNDERPLATING SHALL BE FULL Ni COVERAGE WITH MINIMUM OF 1.25 µM Ni WITHIN CONTACT AREA AND SOLDER AREA.
b). CONTACT AREA:
MINIMUM OF 0.1 µM Au OVER FULL SURFACE AND MINIMUM OF 0.76 µM Au WITHIN 0.6mm INTERNAL DIAMETER.
c). SOLDER AREA:
MINIMUM OF 0.05 µM GOLD FLASH WITHIN 1.0MM INTERNAL DIAMETER OF PCB SOLDER AREA.
 - PACKAGE: TAPE AND REEL, DETAIL SEE DRAWING PK-105402-002.
 - COMPLIANT TO RoHS DIRECTIVE 2011/65/EU/AND ELV DIRECTIVE 2000/53 EC.



DESCRIPTION	PART NO.	DIM-A	DIM-B
SHORTER	1054020022	1.45	1.00
TALLER	1054020032	1.90	1.44

THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX ELECTRONIC TECHNOLOGIES, LLC AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION

EC NO: 108039 DRWN: YXZHENG CHK'D: AYIN APPR: AYIN	2016/09/08 2016/09/08 2017/02/07	GENERAL TOLERANCES (UNLESS SPECIFIED) ANGULAR TOL ± °	DIMENSION UNITS: MM SCALE: 8:1		
	4 PLACES ± 3 PLACES ± 2 PLACES ± 0.1 1 PLACE ± 0.15 0 PLACES ±	DRWN BY: YXZHENG DATE: 2016/03/29	CHK'D BY: YXZHENG DATE: 2016/05/24		8PIN CTKS 105402 CONN.
	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	APPR BY: AYIN DATE: 2016/05/26	PRODUCT CUSTOMER DRAWING		
	A	REV: A	DRAWING SIZE: A3 THIRD ANGLE PROJECTION		SERIES: 105402 MATERIAL NUMBER: SEE TABLE CUSTOMER: GENERAL MARKET
RELEASE STATUS: RELEASE DATE:		DOCUMENT NUMBER: SD-105402-002 DOC TYPE: PSD DOC PART: 000 SHEET NUMBER: 1 OF 1		PRODUCT CUSTOMER DRAWING	